WHAT IS CLAIMED IS:

1. A method for forming a moisture reactive hot melt adhesive comprising
   a) forming a hydroxyl-functional prepolymer by reacting first components comprising a polyol selected from the group consisting of polyether polyols, polyester polyols, and mixtures thereof and a polyisocyanate, the ratio of OH/NCO groups of said first components on an equivalents basis being from 1.05 to 3.0;
   b) admixing second components comprising said hydroxyl-functional prepolymer, a polyol selected from the group consisting of polyether polyols, polyester polyols, and mixtures thereof, and a polyisocyanate, the weight ratio of said hydroxyl-functional prepolymer to said polyol being from 9/1 to 1/9, and the ratio of NCO/OH groups of said second components on an equivalents basis being from 1.5 to 2.2; and
   c) reacting, or allowing to react, said admixture.

2. The method of claim 1 wherein said second components comprise said hydroxyl-functional prepolymer, a crystalline polyester polyol, and a polyisocyanate, the weight ratio of said hydroxyl-functional prepolymer to said polyol being from 9/1 to 1/9, and the ratio of NCO/OH groups of said second components on an equivalents basis being from 1.5 to 2.2.

3. A moisture reactive hot melt adhesive formed by the method of claim 1or claim 2.

4. A method for bonding substrates comprising

forming a moisture reactive hot melt adhesive by the method of claim 1 or claim 2;

heating said hot melt adhesive to a temperature of 90 °C to 140 °C ;

applying said heated hot melt adhesive to a first substrate in the presence of moisture;

contacting said applied heated hot melt adhesive with a second substrate; and

cooling, or allowing to cool, said adhesive.